Packaging and Thermal Characteristics

Products Guide
Product Data Sheets
Package Drawings
Packaging and Thermal Characteristics

Application Notes
White Papers
Software/Hardware Manuals

Xcell Journal Online
Xcell Journal Archives
Inside Out Columns

Glossary of Terms
Literature Request Form
Back to Start Page

Package Drawings

Thermal Packaging Management Application Note XAPP415

460 KB (v1.0) 12/19/01

Package Information NEW!

This section contains the following information:

- Inches and Millimeters
- Dimensions for Xilinx Quad Flat Packs
- Suggested Board Layout of Soldered Pads for BGA Packages
- Recommended PCB Design Rules
- Cavity Up or Cavity Down
- Clockwise or Counterclockwise
- Summary of Thermal Resistance for Packages

Package Electrical Characterization NEW!

This section contains the following information:

- Theoretical Background
- Analytical Formulas for Lead Inductance
- General Measurement Procedure
- Data Acquisition and Package Electrical Database

Component Mass (Weight) by Package Type NEW!

Thermally Enhanced Packaging NEW!

This section contains the following information:

- The Package Offering
- Overview
- Where and When Offered
- Mass Comparison
- Thermal Data for the HQ

Moisture Sensitivity of PSMCs NEW!

This section contains the following information:

- Moisture Induced Cracking During Solder Reflow
- Package Moisture Sensitivity Levels per J-STD-020
- Factory Floor Life
- Dry Bake Recommendation and Dry Bag Policy
- Handling Parts in Sealed Bags

Tape and Reel

This section contains the following information:

- Benefits
- Cover Tape
- Reel
- Bar Code Label
- Shipping Box
- Tape and Reel Packaging

Reflow Soldering Process Guidelines

This section contains the following information:

- Solder Reflow Process
- Soldering Problems Summary
- Typical Conditions for IR Reflow
- Typical Conditions for Vapor Phase Reflow Soldering

Sockets

This section contains the following information:

- Socket Manufacturers
